

Product Information

FELDER ISO-Tin® - SN100-⁴⁰³Cle, SN100-⁴⁰³CLeS, SN100-⁴⁰³Cle+

Refill solders for **SN100-⁴⁰³CL** and **SN100CL™**
according to NIHON SUPERIOR - DE-Patent-No. 69918758 and European-Patent-No. 0985486,
Sn99,9(NiGe) according to DIN EN ISO 9453:2006

Lead-Free FELDER ISO-Tin® refill solders do not contain any substances which are subject to restrictions
according to directive 2011/65/EG („RoHS“).

Item-No.: 561290 ...

Application

In order to compensate the entry of copper into the lead-free alloys SN100-⁴⁰³CL and SN100CL™ in hot air solder levelling units for the PCB production we recommend our copper-free refill solders SN100-⁴⁰³CLe, SN100-⁴⁰³CLeS and SN100-⁴⁰³Cle+. For this purpose, a regular analytical control of the solder bath is inevitable.

As especially during the hot air levelling process the copper entry is particularly high, copper-free refill solders are used for the compensation. Optimal solder characteristics, like improved wetting properties and lowest dross formation, take only effect with a Germanium value of 80 ppm or higher. Here we recommend the refill solder alloy SN100-⁴⁰³CLeS with 100 ppm Ge.

Properties

Melting temperature in °C:	232 (eutectic), reduces in the solder bath to at least 227° C!
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Analysis/Tolerances

Element Content (%)	Sn	Cu	Ag	Ni	Ge	Pb	Au
SN100-⁴⁰³CLe	Rest	≤ 0,05	≤ 0,05	0,04 – 0,06	0,005 – 0,007	≤ 0,05	≤ 0,03
SN100-⁴⁰³CLeS	Rest	≤ 0,05	≤ 0,05	0,04 – 0,06	0,009 – 0,011	≤ 0,05	≤ 0,03
SN100-⁴⁰³CLe+	Rest	≤ 0,05	≤ 0,05	0,13 – 0,17	0,005 – 0,007	≤ 0,05	≤ 0,03

Element Content (%)	Al	As	Bi	Cd	Fe	Sb	Zn
SN100-⁴⁰³CLe	≤ 0,001	≤ 0,03	≤ 0,03	≤ 0,002	≤ 0,02	≤ 0,05	≤ 0,001
SN100-⁴⁰³CLeS							
SN100-⁴⁰³CLe+							

Storage / Advice:

Stored at constant indoor climate durable for an unlimited period!

Delivery Forms

1,0 kg - rods, 330 x 20 x 20 mm,
 4,0 kg - block with closed hanging hole